



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPZ40N04S5-3R9	Issued	09. February 2022
MA#	MA005446214		
Package	PG-TSDSON-8-33	Weight*	36.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.421	1.16	1.16	11580	11580
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		86	
	non noble metal	zinc	7440-66-6	0.012	0.03		342	
	non noble metal	iron	7439-89-6	0.249	0.68		6848	
	non noble metal	copper	7440-50-8	10.102	27.81	28.53	278052	285328
wire	noble metal	gold	7440-57-5	0.026	0.07	0.07	719	719
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1005	
	plastics	epoxy resin	-	1.881	5.18		51781	
	inorganic material	silicondioxide	60676-86-0	16.347	45.00	50.28	449937	502723
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	11017	11017
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2357	2357
solder	non noble metal	tin	7440-31-5	0.013	0.03		346	
	noble metal	silver	7440-22-4	0.016	0.04		432	
	non noble metal	lead	7439-92-1	0.600	1.65	1.72	16518	17296
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.100	0.28		2762	
	non noble metal	copper	7440-50-8	4.075	11.22	11.51	112166	115101
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			16	
	non noble metal	zinc	7440-66-6	0.002	0.01		65	
	non noble metal	iron	7439-89-6	0.047	0.13		1293	
	non noble metal	copper	7440-50-8	1.908	5.25	5.39	52505	53879
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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